

ABSTRACT

Title: CIRCUIT MEMBER, MANUFACTURING METHOD FOR CIRCUIT
5 MEMBERS, SEMICONDUCTOR DEVICE, AND SURFACE LAMINATION
STRUCTURE FOR CIRCUIT MEMBER

A circuit member includes a frame substrate formed, by patterning a rolled
copper plate or a rolled copper alloy plate, with a die pad portion for a semiconductor
10 chip to be mounted thereon, and a lead portion for an electrical connection to the
semiconductor chip, having rough surfaces formed as roughed surfaces on upsides
and lateral wall sides of the die pad portion and the lead portion, and smooth surfaces
formed on downsides of the die pad portion and the lead portion, and the die pad
portion and the lead portion are buried in a sealing resin, having a downside of the
15 lead portion exposed.

Fig. 9